2nd IEEE International Conference on
Artificial Intelligence Circuits and Systems
CAS FOR EFFICIENT, EMBEDDED AI
March 23 - 25, 2020
Genoa, Italy

Call for Sponsorship

As General Co-Chairs of the Organizing Committee, we invite your sponsorship of the 2nd IEEE International Conference on Artificial Intelligence Circuits and Systems (AICAS 2020), which will be held in Genova, Italy, March 23 - 25, 2020. **We want your sponsorship to serve both the conference and your organization.**

About AICAS: AI is driving a revolution in domains ranging from manufacturing, automotive, healthcare, robotics, entertainment, and many others. New computing platforms are required to support the emerging AI algorithms and applications, from cloud servers to edge devices, from system level to circuit level. Facing this new challenge and opportunity, the IEEE Circuit and Systems Society has established the new series of IEEE International Conferences on Artificial Intelligence Circuits and Systems to facilitate state-of-the-art research, innovation and development activities at the frontiers of AI circuits and systems. It brings together academia and industry from the international community to exchange experiences, demonstrate their studies and advance AI technologies.

Following the first successful edition of the conference - held in Taiwan (March 2019) - attended by 300+ international participants from both academia and industry, the second edition is supported by the Neural Systems and Applications Technical Committee of CASS (NSATC) and by committee members from both academia and industry from Europe, US, and Asia who are well-known in the area of AI theory and hardware. AICAS2020 has the support for becoming the major conference for AI that stands between theory, applications, and ASICs. The theme of AICAS2020 is "circuits and systems for efficient, embedded AI", revolving around the development of hardware and computational strategies towards an increase in system efficiency that supports efficient, embedded, smart applications (such as mobile, robotics, automotive).

How your organization can benefit: AICAS2020 is an excellent opportunity for recruiting, branding, and communicating with the best of the international community revolving around the development of real-world AI systems. Your sponsorship presence at the conference with an individual exhibition booth will grant access to a highly targeted group within your practice area and the exhibition and distribution of your marketing and promotional material. It will offer visibility to 300+ participants that span a wide range of backgrounds, from academic and industrial researchers, to entrepreneurs and engineers, to graduate students and postdocs. It will be an opportunity to network with experts and be up to date with the latest trends in the AICAS research community and demonstrate your company's leadership in the field.

On behalf of the AICAS2020 organising committee, we hope you will consider sponsoring the conference in 2020. See below for additional information, including sponsorship levels. Sponsorship applications can be sent to the general chairs. Please do not hesitate to let us know if you have any questions or if there is someone else in your organization we should contact about this opportunity.

Thanks again for your support and we look forward to hearing from you.

Sincerely yours,

Dr. Chiara Bartolozzi
General Co-Chair, AICAS 2020
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General Co-Chair, AICAS 2020
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Diamond [40k Euros]
- Gala dinner sponsor
- Booth space (double size, central in front of coffee break table)
- Best paper award sponsorship (announced during the gala dinner)
- Access to database of attendee CVs who are interested in recruiting contact
- Eight complimentary full-access registration for all conference activities
- Acknowledgement at the opening reception
- Company name and logo on website with link; prominent signage at conference venue

Platinum [20k Euros]
- Welcome apero sponsor
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- Acknowledgement at the opening reception
- Company name and logo on website with link; prominent signage at conference venue

Gold [10k Euros]
- Booth space (standard size)
- Lunch or student travel grant sponsor (3x, announced during the gala dinner)
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- Four complimentary full-access registration for all conference activities
- Acknowledgement at the opening reception
- Company name and logo on website with link; prominent signage at conference venue

Silver [5k Euros]
- Booth space (standard size)
- Access to database of attendee CVs who are interested in recruiting contact
- Two complimentary full-access registration for all conference activities
- Acknowledgement at the opening reception
- Company name and logo on website with link; prominent signage at conference venue

Basic [2k Euros]
- No booth space
- Access to database of attendee CVs who are interested in recruiting contact
- One complimentary full-access registration for all conference activities
- Company name and logo on website with link; prominent signage at conference venue

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